Intel - 5SGXEA7K3F35I4N Datasheet





Welcome to <u>E-XFL.COM</u>

Understanding <u>Embedded - FPGAs (Field</u> <u>Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	234720
Number of Logic Elements/Cells	622000
Total RAM Bits	51200000
Number of I/O	432
Number of Gates	-
Voltage - Supply	0.82V ~ 0.88V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	1152-BBGA, FCBGA
Supplier Device Package	1152-FBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5sgxea7k3f35i4n

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

Table 5 lists the maximum allowed input overshoot voltage and the duration of the overshoot voltage as a percentage of device lifetime. The maximum allowed overshoot duration is specified as a percentage of high time over the lifetime of the device. A DC signal is equivalent to 100% of the duty cycle. For example, a signal that overshoots to 3.95 V can be at 3.95 V for only ~21% over the lifetime of the device; for a device lifetime of 10 years, the overshoot duration amounts to ~2 years.

Symbol	Description	DescriptionCondition (V)Overshoot Duratio @ $T_J = 100^{\circ}$									
		3.8	100	%							
		3.85	64	%							
		3.9	36	%							
		3.95	21	%							
Vi (AC)	AC input voltage	4	12	%							
		4.05	7	%							
		4.1									
		4.15	2	%							
		4.2	1	%							

Table 5. Maximum Allowed Overshoot During Transitions

Figure 1. Stratix V Device Overshoot Duration



I/O Pin Leakage Current

Table 9 lists the Stratix V I/O pin leakage current specifications.

Table 9.	I/O Pin	Leakage	Current for	Stratix V	Devices (1)
----------	---------	---------	--------------------	-----------	-------------

Symbol	Description	Conditions	Min	Тур	Max	Unit
I _I	Input pin	$V_I = 0 V \text{ to } V_{CCIOMAX}$	-30	_	30	μA
I _{OZ}	Tri-stated I/O pin	$V_0 = 0 V \text{ to } V_{\text{CCIOMAX}}$	-30		30	μA

Note to Table 9:

(1) If $V_0 = V_{CCI0}$ to $V_{CCI0Max}$, 100 μ A of leakage current per I/O is expected.

Bus Hold Specifications

Table 10 lists the Stratix V device family bus hold specifications.

Table 10. Bus Hold Parameters for Stratix V Devices

			V _{CCI0}										
Parameter Symbol		Conditions	1.2 V		1.5 V		1.8 V		2.5 V		3.0 V		Unit
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Low sustaining current	I _{SUSL}	V _{IN} > V _{IL} (maximum)	22.5	_	25.0	_	30.0	_	50.0	_	70.0	_	μA
High sustaining current	I _{SUSH}	V _{IN} < V _{IH} (minimum)	-22.5		-25.0	_	-30.0	_	-50.0	_	-70.0		μA
Low overdrive current	I _{odl}	$0V < V_{IN} < V_{CCIO}$		120		160		200	_	300		500	μΑ
High overdrive current	I _{odh}	$0V < V_{IN} < V_{CCIO}$		-120		-160		-200		-300		-500	μΑ
Bus-hold trip point	V _{TRIP}	_	0.45	0.95	0.50	1.00	0.68	1.07	0.70	1.70	0.80	2.00	۷

On-Chip Termination (OCT) Specifications

If you enable OCT calibration, calibration is automatically performed at power-up for I/Os connected to the calibration block. Table 11 lists the Stratix V OCT termination calibration accuracy specifications.

Table 11. OCT Calibration Accuracy Specifications for Stratix V Devices ⁽¹⁾ (Part 1 of 2)

			Calibration Accuracy					
Symbol	Description	Conditions	C1	C2,12	C3,I3, I3YY	C4,14	Unit	
25- $Ω$ R _S	Internal series termination with calibration (25- Ω setting)	V _{CCI0} = 3.0, 2.5, 1.8, 1.5, 1.2 V	±15	±15	±15	±15	%	

			Resistance Tolerance						
Symbol	Description	Conditions	C1	C2,I2	C3, I3, I3YY	C4, I4	Unit		
50-Ω R _S	Internal series termination without calibration (50- Ω setting)	$V_{CCIO} = 1.8$ and 1.5 V	±30	±30	±40	±40	%		
50-Ω R _S	Internal series termination without calibration (50- Ω setting)	V _{CCI0} = 1.2 V	±35	±35	±50	±50	%		
100-Ω R _D	Internal differential termination (100- Ω setting)	V _{CCPD} = 2.5 V	±25	±25	±25	±25	%		

Table 12. OCT Without Calibration Resistance Tolerance Specifications for Stratix V Devices (Part 2 of 2)

Calibration accuracy for the calibrated series and parallel OCTs are applicable at the moment of calibration. When voltage and temperature conditions change after calibration, the tolerance may change.

OCT calibration is automatically performed at power-up for OCT-enabled I/Os. Table 13 lists the OCT variation with temperature and voltage after power-up calibration. Use Table 13 to determine the OCT variation after power-up calibration and Equation 1 to determine the OCT variation without recalibration.

Equation 1. OCT Variation Without Recalibration for Stratix V Devices (1), (2), (3), (4), (5), (6)

$$R_{OCT} \,=\, R_{SCAL} \Big(1 + \langle \frac{dR}{dT} \times \Delta T \rangle \pm \langle \frac{dR}{dV} \times \Delta V \rangle \Big) \label{eq:ROCT}$$

Notes to Equation 1:

- (1) The R_{OCT} value shows the range of OCT resistance with the variation of temperature and V_{CCIO} .
- (2) R_{SCAL} is the OCT resistance value at power-up.
- (3) ΔT is the variation of temperature with respect to the temperature at power-up.
- (4) ΔV is the variation of voltage with respect to the V_{CCIO} at power-up.
- (5) dR/dT is the percentage change of R_{SCAL} with temperature.
- (6) dR/dV is the percentage change of $\mathsf{R}_{\mathsf{SCAL}}$ with voltage.

Table 13 lists the on-chip termination variation after power-up calibration.

Table 13. OCT Variation after Power-Up Calibration for Stratix V Devices (Part 1 of 2)
--

Symbol	Description	V _{CCIO} (V)	Typical	Unit
		3.0	0.0297	
		2.5	0.0344	
dR/dV	OCT variation with voltage without recalibration	1.8	0.0499	%/mV
		1.5	0.0744	
		1.2	0.1241	

I/O	V _{CCIO} (V)			V _{DIF(}	_{DC)} (V)	V _{X(AC)} (V)				V _{CM(DC)} (V)	V _{DIF(AC)} (V)	
Standard	Min	Тур	Max	Min	Max	Min	Тур	Max	Min	Тур	Max	Min	Max
HSTL-12 Class I, II	1.14	1.2	1.26	0.16	V _{CCI0} + 0.3	_	0.5* V _{CCI0}	_	0.4* V _{CCIO}	0.5* V _{CCIO}	0.6* V _{CCI0}	0.3	V _{CCI0} + 0.48
HSUL-12	1.14	1.2	1.3	0.26	0.26	0.5*V _{CCI0} - 0.12	0.5* V _{CCI0}	0.5*V _{CCI0} + 0.12	0.4* V _{CCIO}	0.5* V _{CCIO}	0.6* V _{CCIO}	0.44	0.44

Table 21. Differential HSTL and HSUL I/O Standards for Stratix V Devices (Part 2 of 2)

Table 22. Differential I/O Standard Specifications for Stratix V Devices (7)

I/O	V _{CCI0} (V) ⁽¹⁰⁾			V _{ID} (mV) ⁽⁸⁾			V _{ICM(DC)} (V)			V _{OD} (V) ⁽⁶⁾			V _{OCM} (V) <i>(6)</i>		
Standard	Min	Тур	Max	Min	Condition	Max	Min	Condition	Max	Min	Тур	Max	Min	Тур	Max
PCML	Transmitter, receiver, and input reference clock pins of the high-speed transceived transmitter, receiver, and reference clock I/O pin specifications, refer to the specification of the high-speed transmitter.						rs use o Table	the PC e 23 on	ML I/O s page 18	standard 3.	. For				
2.5 V 2 375 2 5 2 62	2 625	100	V _{CM} =	_	0.05	D _{MAX} ≤ 700 Mbps	1.8	0.247	_	0.6	1.125	1.25	1.375		
LVDS ⁽¹⁾	2.575	2.0	2.025	100	1.25 V	_	1.05	D _{MAX} > 700 Mbps	1.55	0.247	_	0.6	1.125	1.25	1.375
BLVDS (5)	2.375	2.5	2.625	100	_	_	_	_	_	_	_	—	_	—	
RSDS (HIO) ⁽²⁾	2.375	2.5	2.625	100	V _{CM} = 1.25 V	_	0.3	_	1.4	0.1	0.2	0.6	0.5	1.2	1.4
Mini- LVDS (HIO) ⁽³⁾	2.375	2.5	2.625	200	_	600	0.4	_	1.325	0.25	_	0.6	1	1.2	1.4
LVPECL (4	_	_	_	300	_		0.6	D _{MAX} ≤ 700 Mbps	1.8	_	_	_	_	_	_
), (9)				300			1	D _{MAX} > 700 Mbps	1.6						

Notes to Table 22:

(1) For optimized LVDS receiver performance, the receiver voltage input range must be between 1.0 V to 1.6 V for data rates above 700 Mbps, and 0 V to 1.85 V for data rates below 700 Mbps.

(2) For optimized RSDS receiver performance, the receiver voltage input range must be between 0.25 V to 1.45 V.

(3) For optimized Mini-LVDS receiver performance, the receiver voltage input range must be between 0.3 V to 1.425 V.

- (4) For optimized LVPECL receiver performance, the receiver voltage input range must be between 0.85 V to 1.75 V for data rate above 700 Mbps and 0.45 V to 1.95 V for data rate below 700 Mbps.
- (5) There are no fixed V_{ICM} , V_{OD} , and V_{OCM} specifications for BLVDS. They depend on the system topology.
- (6) RL range: $90 \le RL \le 110 \Omega$.
- (7) The 1.4-V and 1.5-V PCML transceiver I/O standard specifications are described in "Transceiver Performance Specifications" on page 18.
- (8) The minimum VID value is applicable over the entire common mode range, VCM.
- (9) LVPECL is only supported on dedicated clock input pins.
- (10) Differential inputs are powered by VCCPD which requires 2.5 V.

Power Consumption

Altera offers two ways to estimate power consumption for a design—the Excel-based Early Power Estimator and the Quartus[®] II PowerPlay Power Analyzer feature.

- You typically use the interactive Excel-based Early Power Estimator before designing the FPGA to get a magnitude estimate of the device power. The Quartus II PowerPlay Power Analyzer provides better quality estimates based on the specifics of the design after you complete place-and-route. The PowerPlay Power Analyzer can apply a combination of user-entered, simulation-derived, and estimated signal activities that, when combined with detailed circuit models, yields very accurate power estimates.
- ***** For more information about power estimation tools, refer to the *PowerPlay Early Power Estimator User Guide* and the *PowerPlay Power Analysis* chapter in the *Quartus II Handbook*.

Switching Characteristics

This section provides performance characteristics of the Stratix V core and periphery blocks.

These characteristics can be designated as Preliminary or Final.

- Preliminary characteristics are created using simulation results, process data, and other known parameters. The title of these tables show the designation as "Preliminary."
- Final numbers are based on actual silicon characterization and testing. The numbers reflect the actual performance of the device under worst-case silicon process, voltage, and junction temperature conditions. There are no designations on finalized tables.

Transceiver Performance Specifications

This section describes transceiver performance specifications.

Table 23 lists the Stratix V GX and GS transceiver specifications.

Table 23.	Transceiver 3	Specifications	for Stratix	V GX	and GS	Devices	(1)	(Part 1	nf 7	۱
Table 20.	TIANSUCIACI	opeonitionationa	IUI UIIAIIA	I UA	anu uu	DEVICES	• •	(1 61 6 1		

Symbol/	Conditions	Tra	nsceive Grade	r Speed 1	Trai	nsceive Grade	r Speed 2	Trai	er Speed e 3	Unit	
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
Reference Clock											
Supported I/O	Dedicated reference clock pin	1.2-V	PCML,	1.4-V PCM	IL, 1.5-∖	/ PCML	, 2.5-V PCN HCSL	1L, Diffe	rential	LVPECL, L\	/DS, and
Standards	RX reference clock pin		1.4-V PCML, 1.5-V PCML, 2.5-V PCML, LVPECL, and LVDS								
Input Reference Clock Frequency (CMU PLL) ⁽⁸⁾	_	40	_	710	40	_	710	40	_	710	MHz
Input Reference Clock Frequency (ATX PLL) ⁽⁸⁾		100		710	100		710	100	_	710	MHz
Rise time	Measure at ±60 mV of differential signal ⁽²⁶⁾			400	_		400			400	ns
Fall time	Measure at ±60 mV of differential signal ⁽²⁶⁾		_	400	_		400			400	μs
Duty cycle		45		55	45		55	45	—	55	%
Spread-spectrum modulating clock frequency	PCI Express® (PCIe [®])	30		33	30		33	30	_	33	kHz

Symbol/	Conditions	Tra	nsceive Grade	r Speed 1	Tra	nsceive Grade	r Speed 2	Trai	r Speed 3	Unit	
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
	85– Ω setting	_	85 ± 30%		_	85 ± 30%		—	85 ± 30%		Ω
Differential on-	100–Ω setting	_	100 ± 30%		_	100 ± 30%		_	100 ± 30%	_	Ω
chip termination resistors ⁽²¹⁾	120–Ω setting	_	120 ± 30%		_	120 ± 30%		_	120 ± 30%	_	Ω
	150-Ω setting	_	150 ± 30%		_	150 ± 30%	_	_	150 ± 30%	_	Ω
	V _{CCR_GXB} = 0.85 V or 0.9 V full bandwidth	_	600	_	_	600	_		600	_	mV
V _{ICM} (AC and DC	V _{CCR_GXB} = 0.85 V or 0.9 V half bandwidth		600	_		600	_		600	_	mV
(oupled)	V _{CCR_GXB} = 1.0 V/1.05 V full bandwidth	_	700	_	_	700	_	_	700	_	mV
	V _{CCR_GXB} = 1.0 V half bandwidth		750	_	_	750	_	_	750	_	mV
t _{LTR} ⁽¹¹⁾	—	_	_	10	_	—	10	_	—	10	μs
t _{LTD} ⁽¹²⁾	—	4	_		4	—		4	-	—	μs
t _{LTD_manual} ⁽¹³⁾	—	4			4	—		4	—	—	μs
t _{LTR_LTD_manual} ⁽¹⁴⁾	—	15	_		15	—		15	—	—	μs
Run Length		_		200	_	—	200	_	—	200	UI
Programmable equalization (AC Gain) ⁽¹⁰⁾	Full bandwidth (6.25 GHz) Half bandwidth (3.125 GHz)		_	16	_	_	16	_		16	dB

 Table 23. Transceiver Specifications for Stratix V GX and GS Devices ⁽¹⁾ (Part 4 of 7)

Table 24 shows the maximum transmitter data rate for the clock network.

Table 24. Clock Network Maximum Data Rate Transmitter Specifications (1)

		ATX PLL			CMU PLL ⁽²⁾)	fPLL			
Clock Network	Non- bonded Mode (Gbps)	Bonded Mode (Gbps)	Channel Span	Non- bonded Mode (Gbps)	Bonded Mode (Gbps)	Channel Span	Non- bonded Mode (Gbps)	Bonded Mode (Gbps)	Channel Span	
x1 ⁽³⁾	14.1	_	6	12.5	_	6	3.125	—	3	
x6 ⁽³⁾	_	14.1	6	—	12.5	6	—	3.125	6	
x6 PLL Feedback ⁽⁴⁾	_	14.1	Side- wide	_	12.5	Side- wide	_	_	_	
xN (PCIe)	_	8.0	8	—	5.0	8	—	—	—	
xN (PCIe) xN (Native PHY IP) -	8.0	8.0	Up to 13 channels above and below PLL	7 00	7 00	Up to 13 channels above	3 125	3 125	Up to 13 channels above	
	_	8.01 to 9.8304	Up to 7 channels above and below PLL	7.99	7.99	and below PLL	0.120	0.120	and below PLL	

Notes to Table 24:

(1) Valid data rates below the maximum specified in this table depend on the reference clock frequency and the PLL counter settings. Check the MegaWizard message during the PHY IP instantiation.

(2) ATX PLL is recommended at 8 Gbps and above data rates for improved jitter performance.

(3) Channel span is within a transceiver bank.

(4) Side-wide channel bonding is allowed up to the maximum supported by the PHY IP.





Figure 3 shows the Stratix V AC gain curves for GX channels.

Figure 3. AC Gain Curves for GX Channels (full bandwidth)

Stratix V GT devices contain both GX and GT channels. All transceiver specifications for the GX channels not listed in Table 28 are the same as those listed in Table 23.

Table 28 lists the Stratix V GT transceiver specifications.

Table 28. Transceiver Specifications for Stratix V GT Devices (Part 2 of 5)⁽¹⁾

Symbol/	Conditions	S	Transceive peed Grade	r 2	SI	r 3	Unit	
Description		Min	Тур	Max	Min	Тур	Max	
	100 Hz	—	—	-70			-70	
Transmitter REFCLK	1 kHz		_	-90	_	_	-90	
Phase Noise (622	10 kHz		—	-100	_		-100	dBc/Hz
MHz) ⁽¹⁸⁾	100 kHz			-110			-110	
	\geq 1 MHz	—	—	-120	_	_	-120	
Transmitter REFCLK Phase Jitter (100 MHz) ⁽¹⁵⁾	10 kHz to 1.5 MHz (PCle)	_	_	3		_	3	ps (rms)
RREF ⁽¹⁷⁾	_	_	1800 ± 1%	—	_	1800 ± 1%	_	Ω
Transceiver Clocks								
fixedclk clock frequency	PCIe Receiver Detect	_	100 or 125	_	_	100 or 125	_	MHz
Reconfiguration clock (mgmt_clk_clk) frequency	_	100	_	125	100	_	125	MHz
Receiver	•							
Supported I/O Standards	_		1.4-V PCML	., 1.5-V PCMI	L, 2.5-V PCI	VIL, LVPEC	L, and LVDS	6
Data rate (Standard PCS) ⁽²¹⁾	GX channels	600	_	8500	600	_	8500	Mbps
Data rate (10G PCS) ⁽²¹⁾	GX channels	600	_	12,500	600	_	12,500	Mbps
Data rate	GT channels	19,600	—	28,050	19,600		25,780	Mbps
Absolute V _{MAX} for a receiver pin ⁽³⁾	GT channels	_	_	1.2	_	_	1.2	V
Absolute V _{MIN} for a receiver pin	GT channels	-0.4	_	—	-0.4	_	_	V
Maximum peak-to-peak	GT channels	_		1.6	—	_	1.6	V
differential input voltage V _{ID} (diff p-p) before device configuration ⁽²⁰⁾	GX channels				(8)			
	GT channels							
Maximum peak-to-peak differential input voltage V_{ID} (diff p-p) after device	V _{CCR_GTB} = 1.05 V (V _{ICM} = 0.65 V)	_	_	2.2	_	—	2.2	V
	GX channels		1	1 1	(8)			1
Minimum differential	GT channels	200	_	—	200		_	mV
eye opening at receiver serial input pins ⁽⁴⁾ , ⁽²⁰⁾	GX channels			·	(8)			

PLL Specifications

Table 31 lists the Stratix V PLL specifications when operating in both the commercial junction temperature range (0° to 85° C) and the industrial junction temperature range (-40° to 100° C).

Table 31. PLL Specifications for Stratix V Devices (Part 1 of 3)

Symbol	Parameter	Min	Тур	Max	Unit
	Input clock frequency (C1, C2, C2L, I2, and I2L speed grades)	5		800 (1)	MHz
f _{IN}	Input clock frequency (C3, I3, I3L, and I3YY speed grades)	5		800 (1)	MHz
	Input clock frequency (C4, I4 speed grades)	5	—	650 ⁽¹⁾	MHz
f _{INPFD}	Input frequency to the PFD	5	—	325	MHz
f _{FINPFD}	Fractional Input clock frequency to the PFD	50	—	160	MHz
	PLL VCO operating range (C1, C2, C2L, I2, I2L speed grades)	600	_	1600	MHz
f _{VCO} (9)	PLL VCO operating range (C3, I3, I3L, I3YY speed grades)	600		1600	MHz
	PLL VCO operating range (C4, I4 speed grades)	600	—	1300	MHz
t _{einduty}	Input clock or external feedback clock input duty cycle	40	—	60	%
	Output frequency for an internal global or regional clock (C1, C2, C2L, I2, I2L speed grades)	_	_	717 ⁽²⁾	MHz
f _{OUT}	Output frequency for an internal global or regional clock (C3, I3, I3L speed grades)			650 ⁽²⁾	MHz
	Output frequency for an internal global or regional clock (C4, I4 speed grades)			580 ⁽²⁾	MHz
	Output frequency for an external clock output (C1, C2, C2L, I2, I2L speed grades)			800 ⁽²⁾	MHz
f _{OUT_EXT}	Output frequency for an external clock output (C3, I3, I3L speed grades)			667 ⁽²⁾	MHz
	Output frequency for an external clock output (C4, I4 speed grades)			553 ⁽²⁾	MHz
t _{outduty}	Duty cycle for a dedicated external clock output (when set to 50%)	45	50	55	%
t _{FCOMP}	External feedback clock compensation time	_		10	ns
f _{dyconfigclk}	Dynamic Configuration Clock used for mgmt_clk and scanclk		_	100	MHz
t _{LOCK}	Time required to lock from the end-of-device configuration or deassertion of areset			1	ms
t _{DLOCK}	Time required to lock dynamically (after switchover or reconfiguring any non-post-scale counters/delays)			1	ms
	PLL closed-loop low bandwidth	—	0.3	—	MHz
f _{CLBW}	PLL closed-loop medium bandwidth	—	1.5	—	MHz
	PLL closed-loop high bandwidth (7)	—	4	-	MHz
t _{PLL_PSERR}	Accuracy of PLL phase shift	—	—	±50	ps
t _{ARESET}	Minimum pulse width on the areset signal	10	—	_	ns

Symbol	Conditiono		C1		C2,	C2L, I	2, I2L	C3,	13, 131	., I3YY	r C4,14			Unit
Symbol	Conditions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	UIIIL
Transmitter														
	SERDES factor J = 3 to 10 ⁽⁹⁾ , ⁽¹¹⁾ , ⁽¹²⁾ , ⁽¹³⁾ , ⁽¹⁴⁾ , ⁽¹⁵⁾ , ⁽¹⁶⁾	(6)	_	1600	(6)	_	1434	(6)	_	1250	(6)	_	1050	Mbps
True Differential I/O Standards - f _{HSDR} (data	SERDES factor J ≥ 4 LVDS TX with DPA (12), (14), (15), (16)	(6)		1600	(6)		1600	(6)		1600	(6)	_	1250	Mbps
- f _{HSDR} (data rate)	SERDES factor J = 2, uses DDR Registers	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	(6)		(7)	Mbps
	SERDES factor J = 1, uses SDR Register	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	Mbps
Emulated Differential I/O Standards with Three External Output Resistor Networks - f _{HSDR} (data rate) ⁽¹⁰⁾	SERDES factor J = 4 to 10 $(^{17})$	(6)		1100	(6)		1100	(6)		840	(6)		840	Mbps
t _{x Jitter} - True Differential	Total Jitter for Data Rate 600 Mbps - 1.25 Gbps		_	160		_	160		_	160			160	ps
I/O Standards	Total Jitter for Data Rate < 600 Mbps		_	0.1			0.1			0.1		_	0.1	UI
t _{x Jitter} - Emulated Differential I/O Standards	Total Jitter for Data Rate 600 Mbps - 1.25 Gbps	_	_	300	_		300	_	_	300	_		325	ps
with Three External Output Resistor Network	Total Jitter for Data Rate < 600 Mbps	_	_	0.2	_	_	0.2	_	_	0.2	_	_	0.25	UI

Table 36. High-Speed I/O Specifications for Stratix V Devices (1), (2) (Part 2 of 4)

	0		C1		C2,	C2L, I	2, I2L	C3,	13, 131	., I 3YY	r C4,14			
Symbol	Conditions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
t _{duty}	Transmitter output clock duty cycle for both True and Emulated Differential I/O Standards	45	50	55	45	50	55	45	50	55	45	50	55	%
	True Differential I/O Standards	_	_	160	_	_	160	_	_	200	_	_	200	ps
t _{rise} & t _{fall}	Emulated Differential I/O Standards with three external output resistor networks			250			250			250			300	ps
	True Differential I/O Standards	_	_	150	_	_	150	_	_	150	_	_	150	ps
TCCS	Emulated Differential I/O Standards			300			300	_		300			300	ps
Receiver														
	SERDES factor J = 3 to 10 (11), (12), (13), (14), (15), (16)	150		1434	150	_	1434	150	_	1250	150	_	1050	Mbps
True Differential 1/0 Standards	SERDES factor J ≥ 4 LVDS RX with DPA (12), (14), (15), (16)	150	_	1600	150	_	1600	150	_	1600	150	_	1250	Mbps
- f _{HSDRDPA} (data rate)	SERDES factor J = 2, uses DDR Registers	(6)		(7)	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	Mbps
	SERDES factor J = 1, uses SDR Register	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	(6)		(7)	Mbps

Table 36. High-Speed I/O Specifications for Stratix V Devices (1), (2) (Part 3 of 4)

Figure 7 shows the dynamic phase alignment (DPA) lock time specifications with the DPA PLL calibration option enabled.

Figure 7. DPA Lock Time Specification with DPA PLL Calibration Enabled

rx_reset			
rx_dpa_locked			<u> </u>
			-

Table 37 lists the DPA lock time specifications for Stratix V devices.

Table 37. DPA Lock Time Specifications for Stratix V GX Devices Only (1), (2), (3)

Standard	Training Pattern	Number of Data Transitions in One Repetition of the Training Pattern	Number of Repetitions per 256 Data Transitions ⁽⁴⁾	Maximum
SPI-4	00000000001111111111	2	128	640 data transitions
Parallel Rapid I/O	00001111	2	128	640 data transitions
	10010000	4	64	640 data transitions
Miscellaneous	10101010	8	32	640 data transitions
Wiscenareous	01010101	8	32	640 data transitions

Notes to Table 37:

(1) The DPA lock time is for one channel.

(2) One data transition is defined as a 0-to-1 or 1-to-0 transition.

(3) The DPA lock time stated in this table applies to both commercial and industrial grade.

(4) This is the number of repetitions for the stated training pattern to achieve the 256 data transitions.

Figure 8 shows the **LVDS** soft-clock data recovery (CDR)/DPA sinusoidal jitter tolerance specification for a data rate \geq 1.25 Gbps. Table 38 lists the **LVDS** soft-CDR/DPA sinusoidal jitter tolerance specification for a data rate \geq 1.25 Gbps.





Clock	Parameter	Symbol	C1		C2, C2L, I2, I2L		C3, I3 I3	8, 13L , YY	C4	Unit	
Network			Min	Max	Min	Max	Min	Max	Min	Max	
	Clock period jitter	$t_{JIT(per)}$	-25	25	-25	25	-30	30	-35	35	ps
PHY Clock	Cycle-to-cycle period jitter	$t_{\rm JIT(cc)}$	-50	50	-50	50	-60	60	-70	70	ps
	Duty cycle jitter	$t_{JIT(duty)}$	-37.5	37.5	-37.5	37.5	-45	45	-56	56	ps

Table 42. Memory Output Clock Jitter Specification for Stratix V Devices (1), (Part 2 of 2) (2), (3)

Notes to Table 42:

(1) The clock jitter specification applies to the memory output clock pins generated using differential signal-splitter and DDIO circuits clocked by a PLL output routed on a PHY, regional, or global clock network as specified. Altera recommends using PHY clock networks whenever possible.

(2) The clock jitter specification applies to the memory output clock pins clocked by an integer PLL.

(3) The memory output clock jitter is applicable when an input jitter of 30 ps peak-to-peak is applied with bit error rate (BER) -12, equivalent to 14 sigma.

OCT Calibration Block Specifications

Table 43 lists the OCT calibration block specifications for Stratix V devices.

Table 43. OCT Calibration Block Specifications for Stratix V Devices

Symbol	Description	Min	Тур	Max	Unit
OCTUSRCLK	Clock required by the OCT calibration blocks	—	—	20	MHz
T _{OCTCAL}	Number of OCTUSRCLK clock cycles required for OCT $\rm R_S/R_T$ calibration		1000	_	Cycles
T _{OCTSHIFT}	Number of OCTUSRCLK clock cycles required for the OCT code to shift out	_	32	_	Cycles
T _{RS_RT}	Time required between the dyn_term_ctrl and oe signal transitions in a bidirectional I/O buffer to dynamically switch between OCT R_S and R_T (Figure 10)		2.5		ns

Figure 10 shows the timing diagram for the oe and dyn_term_ctrl signals.

Figure 10. Timing Diagram for oe and dyn_term_ctrl Signals



Symbol	Description	Min	Max	Unit
t _{JPH}	JTAG port hold time	5	—	ns
t _{JPCO}	JTAG port clock to output	—	11 ⁽¹⁾	ns
t _{JPZX}	JTAG port high impedance to valid output	—	14 ⁽¹⁾	ns
t _{JPXZ}	JTAG port valid output to high impedance	—	14 ⁽¹⁾	ns

Table 46. JTAG Timing Parameters and Values for Stratix V Devices

Notes to Table 46:

(1) A 1 ns adder is required for each V_{CCI0} voltage step down from 3.0 V. For example, $t_{JPC0} = 12$ ns if V_{CCI0} of the TDO I/O bank = 2.5 V, or 13 ns if it equals 1.8 V.

(2) The minimum TCK clock period is 167 ns if VCCBAT is within the range 1.2V-1.5V when you perform the volatile key programming.

Raw Binary File Size

For the POR delay specification, refer to the "POR Delay Specification" section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices".

Table 47 lists the uncompressed raw binary file (.rbf) sizes for Stratix V devices.

Family	Device Package Co		Configuration .rbf Size (bits)	IOCSR .rbf Size (bits) ^{(4), (5)}
	500742	H35, F40, F35 ⁽²⁾	213,798,880	562,392
	JOUNAS	H29, F35 ⁽³⁾	137,598,880	564,504
	5SGXA4	—	213,798,880	563,672
	5SGXA5	—	269,979,008	562,392
	5SGXA7	—	269,979,008	562,392
Stratix V GX	5SGXA9	—	342,742,976	700,888
	5SGXAB	—	342,742,976	700,888
	5SGXB5	—	270,528,640	584,344
	5SGXB6	—	270,528,640	584,344
	5SGXB9	_	342,742,976	700,888
	5SGXBB	—	342,742,976	700,888
Stratix V CT	5SGTC5	—	269,979,008	562,392
	5SGTC7	_	269,979,008	562,392
	5SGSD3	—	137,598,880	564,504
	500004	F1517	213,798,880	563,672
Strativ V CS	J303D4		137,598,880	564,504
	5SGSD5	—	213,798,880	563,672
	5SGSD6		293,441,888	565,528
	5SGSD8	—	293,441,888	565,528

Table 47. Uncompressed .rbf Sizes for Stratix V Devices

Configuration Scheme	Decompression	Design Security	DCLK-to-DATA[] Ratio
	Disabled	Disabled	1
FPP ×32	Disabled	Enabled	4
	Enabled	Disabled	8
	Enabled	Enabled	8

Table 49.	DCLK-to-DATA[]	Ratio ⁽¹⁾	(Part 2 of 2)
-----------	----------------	----------------------	---------------

Note to Table 49:

(1) Depending on the DCLK-to-DATA [] ratio, the host must send a DCLK frequency that is r times the data rate in bytes per second (Bps), or words per second (Wps). For example, in FPP ×16 when the DCLK-to-DATA [] ratio is 2, the DCLK frequency must be 2 times the data rate in Wps. Stratix V devices use the additional clock cycles to decrypt and decompress the configuration data.

Figure 11 shows the configuration interface connections between the Stratix V device and a MAX II or MAX V device for single device configuration.

Figure 11. Single Device FPP Configuration Using an External Host



Notes to Figure 11:

- (1) Connect the resistor to a supply that provides an acceptable input signal for the Stratix V device. V_{CCPGM} must be high enough to meet the V_{IH} specification of the I/O on the device and the external host. Altera recommends powering up all configuration system I/Os with V_{CCPGM} .
- (2) You can leave the nCEO pin unconnected or use it as a user I/O pin when it does not feed another device's nCE pin.
- (3) The MSEL pin settings vary for different data width, configuration voltage standards, and POR delay. To connect MSEL, refer to the MSEL Pin Settings section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (4) If you use FPP ×8, use DATA [7..0]. If you use FPP ×16, use DATA [15..0].

IF the DCLK-to-DATA[] ratio is greater than 1, at the end of configuration, you can only stop the DCLK (DCLK-to-DATA[] ratio – 1) clock cycles after the last data is latched into the Stratix V device.

Paramotor	Available Min		Fast Model		Slow Model							
(1)	Settings	Offset (2)	Industrial	Commercial	C1	C2	C3	C4	12	13, 13YY	14	Unit
D3	8	0	1.587	1.699	2.793	2.793	2.992	3.192	2.811	3.047	3.257	ns
D4	64	0	0.464	0.492	0.838	0.838	0.924	1.011	0.843	0.920	1.006	ns
D5	64	0	0.464	0.493	0.838	0.838	0.924	1.011	0.844	0.921	1.006	ns
D6	32	0	0.229	0.244	0.415	0.415	0.458	0.503	0.418	0.456	0.499	ns

Table 58.	IOE Pro	grammable De	ay for	Stratix V	V Devices	(Part 2 of 2)
-----------	---------	--------------	--------	-----------	-----------	--------------	---

Notes to Table 58:

(1) You can set this value in the Quartus II software by selecting D1, D2, D3, D5, and D6 in the Assignment Name column of Assignment Editor.

(2) Minimum offset does not include the intrinsic delay.

Programmable Output Buffer Delay

Table 59 lists the delay chain settings that control the rising and falling edge delays of the output buffer. The default delay is 0 ps.

Symbol	Parameter	Typical	Unit
		0 (default)	ps
Dauman	Rising and/or falling edge	25	ps
DOUTBUF	delay	50	ps
		75	ps

Note to Table 59:

(1) You can set the programmable output buffer delay in the Quartus II software by setting the Output Buffer Delay Control assignment to either positive, negative, or both edges, with the specific values stated here (in ps) for the Output Buffer Delay assignment.

Glossary

Table 60 lists the glossary for this chapter.

Table 60. Glossary (Part 1 of 4)

Letter	Subject	Definitions
Α		
В	—	—
С		
D	—	_
E	—	_
	f _{HSCLK}	Left and right PLL input clock frequency.
F	f _{HSDR}	High-speed I/O block—Maximum and minimum LVDS data transfer rate (f _{HSDR} = 1/TUI), non-DPA.
	f _{hsdrdpa}	High-speed I/O block—Maximum and minimum LVDS data transfer rate (f _{HSDRDPA} = 1/TUI), DPA.

Document Revision History

Table 61 lists the revision history for this chapter.

 Table 61. Document Revision History (Part 1 of 3)

Date	Version	Changes			
June 2018	3.9	 Added the "Stratix V Device Overshoot Duration" figure. 			
April 2017		Added a footnote to the "High-Speed I/O Specifications for Stratix V Devices" table.			
		 Changed the minimum value for t_{CD2UMC} in the "PS Timing Parameters for Stratix V Devices" table. 			
		 Changed the condition for 100-Ω R_D in the "OCT Without Calibration Resistance Tolerance Specifications for Stratix V Devices" table. 			
	3.8	 Changed the minimum value for t_{CD2UMC} in the "AS Timing Parameters for AS '1 and AS '4 Configurations in Stratix V Devices" table 			
		 Changed the minimum value for t_{CD2UMC} in the "FPP Timing Parameters for Stratix V Devices When the DCLK-to-DATA[] Ratio is >1" table. 			
		 Changed the minimum value for t_{CD2UMC} in the "FPP Timing Parameters for Stratix V Devices When the DCLK-to-DATA[] Ratio is >1" table. 			
		 Changed the minimum number of clock cycles value in the "Initialization Clock Source Option and the Maximum Frequency" table. 			
June 2016	3.7	 Added the V_{ID} minimum specification for LVPECL in the "Differential I/O Standard Specifications for Stratix V Devices" table 			
		 Added the I_{OUT} specification to the "Absolute Maximum Ratings for Stratix V Devices" table. 			
December 2015	3.6	Added a footnote to the "High-Speed I/O Specifications for Stratix V Devices" table.			
D 0045	3.5	 Changed the transmitter, receiver, and ATX PLL data rate specifications in the "Transceiver Specifications for Stratix V GX and GS Devices" table. 			
		 Changed the configuration .rbf sizes in the "Uncompressed .rbf Sizes for Stratix V Devices" table. 			
		• Changed the data rate specification for transceiver speed grade 3 in the following tables:			
		 "Transceiver Specifications for Stratix V GX and GS Devices" 			
		 "Stratix V Standard PCS Approximate Maximum Date Rate" 			
		 "Stratix V 10G PCS Approximate Maximum Data Rate" 			
July 2015	3.4	 Changed the conditions for reference clock rise and fall time, and added a note to the "Transceiver Specifications for Stratix V GX and GS Devices" table. 			
		 Added a note to the "Minimum differential eye opening at receiver serial input pins" specification in the "Transceiver Specifications for Stratix V GX and GS Devices" table. 			
		 Changed the t_{c0} maximum value in the "AS Timing Parameters for AS '1 and AS '4 Configurations in Stratix V Devices" table. 			
		 Removed the CDR ppm tolerance specification from the "Transceiver Specifications for Stratix V GX and GS Devices" table. 			

Table 61. Document Revision History (Part 2 of 3)

Date	Version	Changes			
		 Added the I3YY speed grade and changed the data rates for the GX channel in Table 1. 			
		 Added the I3YY speed grade to the V_{CC} description in Table 6. 			
		 Added the I3YY speed grade to V_{CCHIP_L}, V_{CCHIP_R}, V_{CCHSSI_L}, and V_{CCHSSI_R} descriptions in Table 7. 			
		■ Added 240-Ω to Table 11.			
		Changed CDR PPM tolerance in Table 23.			
		 Added additional max data rate for fPLL in Table 23. 			
		 Added the I3YY speed grade and changed the data rates for transceiver speed grade 3 in Table 25. 			
		 Added the I3YY speed grade and changed the data rates for transceiver speed grade 3 in Table 26. 			
		 Changed CDR PPM tolerance in Table 28. 			
		 Added additional max data rate for fPLL in Table 28. 			
		 Changed the mode descriptions for MLAB and M20K in Table 33. 			
		 Changed the Max value of f_{HSCLK_OUT} for the C2, C2L, I2, I2L speed grades in Table 36. 			
November 2014	3.3	 Changed the frequency ranges for C1 and C2 in Table 39. 			
		 Changed the .rbf file sizes for 5SGSD6 and 5SGSD8 in Table 47. 			
		 Added note about nSTATUS to Table 50, Table 51, Table 54. 			
		 Changed the available settings in Table 58. 			
		 Changed the note in "Periphery Performance". 			
		 Updated the "I/O Standard Specifications" section. 			
		 Updated the "Raw Binary File Size" section. 			
		 Updated the receiver voltage input range in Table 22. 			
		 Updated the max frequency for the LVDS clock network in Table 36. 			
		■ Updated the DCLK note to Figure 11.			
		 Updated Table 23 VO_{CM} (DC Coupled) condition. 			
		Updated Table 6 and Table 7.			
		 Added the DCLK specification to Table 55. 			
		Updated the notes for Table 47.			
		 Updated the list of parameters for Table 56. 			
November 2013	3.2	Updated Table 28			
November 2013	3.1	Updated Table 33			
November 2013	3.0	Updated Table 23 and Table 28			
October 2013	2.9	 Updated the "Transceiver Characterization" section 			
		 Updated Table 3, Table 12, Table 14, Table 19, Table 20, Table 23, Table 24, Table 28, Table 30, Table 31, Table 32, Table 33, Table 36, Table 39, Table 40, Table 41, Table 42, Table 47, Table 53, Table 58, and Table 59 			
Uctober 2013	2.8	 Added Figure 1 and Figure 3 			
		 Added the "Transceiver Characterization" section 			
		 Removed all "Preliminary" designations. 			